

Development of a Low-Power Read-Out System Using CMOS ASICs for a μ -PIC.

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Abstract : For astronomical observations, we have been developing an Electron Tracking Compton Camera (ETCC) based on a gaseous time projection chamber (µ-TPC) with a micro pixel gaseous chamber (µ-PIC), and scintillation cameras. With this camera, we have the balloon born experiment named SMILE. In a balloon-borne experiment, the space and power consumption are seriously restricted by capacity of batteries.

We have developed low power CMOS Front-End ASIC for a µ-PIC in a collaboration with KEK. The ASIC chip, named FE2009bal, integrated 16 channels of a charge sensitive frontend amplifier, a shaper, and a discriminator has been designed and fabricated with the TSMC 0.5 µm process. The power consumption of the chip is about 18mW/ch. The readout board based on the ASIC has also been developed. This board is implemented of 8 FE2009bal chips and Xilinx FPGA, and processes 128 analog signals from the μ -PIC.

The total power consumption of the readout board is about 66W for a $(30 \text{ cm})^2 \mu$ -PIC (1536 strips).

Detector ~ Electron Tracking Compton Camera ~



Schematic view of the μ -PIC (left) photographs of 10cm²µ-PIC, (bottom right) and its microphotograph (upper right).



For the sub MeV to MeV gamma-ray observation in astronomy, we have been developing an Electron Tracking Compton Camera (ETCC). The Camera consists of a gaseous time projection chamber (μ -TPC) [1] with μ -PIC [2][3], which detects the 3D-track and the energy of the recoil electron, and a scintillation camera, which detects the absorption point and the energy of the scattered gamma ray. By using these four pieces of information, we can completely reconstruct the Compton scattering event by event, and obtain a fully ray-traced gamma-ray image[1].

With this camera, we have planned the balloon experiments named SMILE (Sub-MeV gamma-ray Imaging Loaded-on-balloon Experiment).

> (10cm)³ ETCC @Sanriku, JPN (2006) **SMILE- I** [4] □Operation test of ETCC @ 35km □ Measurement of Diffuse cosmic and atmospheric gamma rays □512ch readout : ~70W □ATLAS TGC ASD[5] (Bipolar Process) : 59mW/ch (30cm)³ ETCC (2012~) SMILE-II Observation of Crab or Cyg X-1 □1500ch readout

\square80W for μ -TPC Read-out

We took signals from the $10 \text{ cm}^3 \text{ }\mu\text{-}\text{TPC}$ using test boards with 8 FE2009bal chips. We have successfully measured spectrum of X-ray from ¹⁰⁹Cd source, and got tracks of cosmic-ray muons.



Photograph of the detector setup.

Detector Status • (10cm)² μ-PIC •µ-PIC Anode : 430V • $\Delta GEM = 400V (P140-\phi70-100t LCP)$ • Effectine Volume : 2.5cm×2.5cm×15cm

• Gas : Ar 90% + C_2H_6 10% 1atm (sealed) •Stable gas gain : ~40000





Observed tracks of cosmic-ray muons.

In a balloon-borne experiment the power consumption and space is seriously restricted. Thus we need lowpower and fast readout system.

 \Box Super pressure balloon ~ 10 days □4000ch readout ATLAS TGC ASD 64ch board Roadmap of the SMILE

(40cm)³ ETCC

Requirement to new Readout System

- Low power Consumption.
- (less than 80W for a $(30 \text{ cm})^2 \mu$ -PIC)
- Small size and high integration.
- Input dynamic range : -1pC ~ 1pC
- ENC<6000 e⁻ @ Cd = 100pF

2, New ASIC Chip : FE2009bal

We have developed CMOS ASIC for µ-TPC with KEK to improve the power consumption. We designed new ASIC chip "FE2009bal" using SPICE simulator. The chip is fabricated with <u>"TSMC 0.5µm CMOS process</u>". The chip contains 16 channels in a LQFP100-pin package. In this chip, the power consumption is reduced to 18mW/ch, and other parameters are all satisfy our



Specification of FE2009bal TSMC 0.5µm CMOS process. Preamplifier with a gain of <u>0.6V/pC</u>. •16ch sum amp with a gain of 0.8V/pC. Comparator with CMOS 2.5V output. 6bit DAC for calibrate channel variety. ENC ~6000 e^{-} at Cd = 100pF. Required voltage +/-2.5V,GND. • 16 channels in 1 chip.



4, Readout Board Based on FE2009bal

3, FE2009bal Chip Test with μ -PIC

The new readout board based on FE2009bal chips has also been developed. This board processes 128 analog signals from the μ -PIC. An FPGA is also employed to process digital signal from ASICs and ADCs. The hit patterns, clocks, and wave forms of tracks are calculated in FPGA and sent to a VME memory board. The total power consumption of this readout board is about 66W for a $(30 \text{ cm})^2 \mu$ -PIC.



